AMENDMENT UNDER 37 C.F.R. § 1.312

Serial Number: 10/772,606 Filing Date: February 5, 2004

Title: INTEGRATED CIRCUITS USING OPTICAL FIBER INTERCONNECTS FORMED THROUGH A SEMICONDUCTOR WAFER

## Conclusion

The specification has been amended to update the priority data. It is respectfully submitted that these changes do not introduce new matter, and the claims are allowable without further search or consideration. Therefore, entry is appropriate under Rule 312, and is respectfully requested.

Respectfully submitted,

JOSEPH E. GEUSIC ET AL.

By their Representatives,

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.

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Dkt: 303.390US4

P.O. Box 2938

Minneapolis, MN 55402

(612) 373-6969

Date October 27, 2005 By

Viet V. Tong Reg. No. 45,416

CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail, in an envelope addressed to: Mail Stop Issue Fee, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on this 28 day of October, 2005.

Eric H. Olson

Name